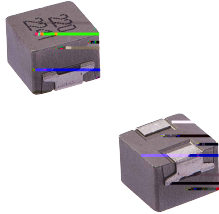


# MDA HT Series

## SMD Low Profile High Current Molded Inductor

### Size 8054



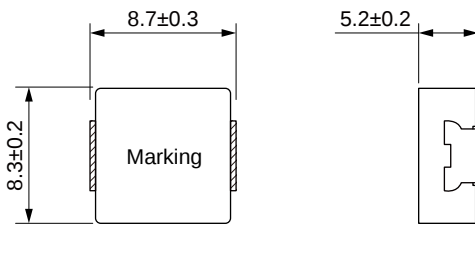
#### FEATURES

- Low loss realized with low DCR.
- ΣΡύοτ ΡύΧ όΐαα ΩύΩσΣ ΣΐΣ ύύ ΌύΨμύσάύΣ ΌύΩσύóΐΌΓύΩ .
- 100% Lead(Pb)-Free and RoHS compliant.
- High performance (Isat) realized by metal dust core.
- !9/ v ξΐτΡάύΣΣ.
- ημΣοτΓ° ύΣΨμΣοτύΐοΣ ύύ / ΩΩΌΠΐΣΩΩ° σΣΡύ ύΣΨμΣοτύΐοΣ οΩσΣ
- νΐτΩΓύbl t / {

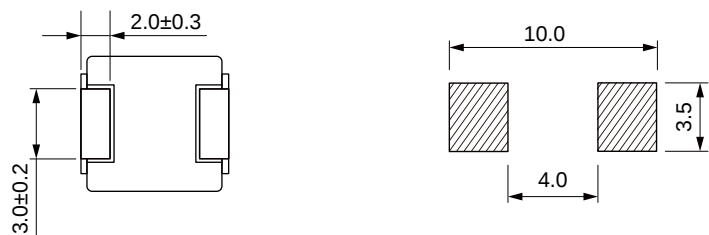
#### APPLICATION

- ΙΣτΣΡτΨμσ ύτΩΡ ΡτΨμσ τΩΣ ΩΩύΣοΩύó ΡΩ° ΓΓ°
- HVAC
- 5ύύοσ ΧΩΩΣύΧ ΡΩ° τΩΣ σΣτύ ΌύΩύóύΡ
- Audio subsystem
- Digital instrument cluster
- ΩΩ° 3Σ° ΓΩΌΡΣ ΛΩύύύτΩΨΣΩύ τΩΣ ΩτΦΩ° τΓύΩ

#### Dimensions: [mm]



#### Land Pattern: [mm]



#### Electrical Properties:

|  | ±20% | 15.5 | 14.0 | 22.0 | 19.0 | 4.0  | 4.8  |
|--|------|------|------|------|------|------|------|
|  | ±20% | 14.5 | 13.0 | 18.0 | 15.5 | 6.5  | 7.8  |
|  | ±20% | 13.5 | 12.5 | 16.3 | 14.0 | 9.5  | 11.4 |
|  | ±20% | 11.0 | 10.0 | 12.0 | 11.0 | 13.0 | 15.6 |
|  | ±20% | 11.0 | 9.0  | 15.0 | 13.0 | 18.0 | 22.0 |
|  | ±20% | 7.8  | 6.8  | 9.0  | 7.7  | 29.0 | 35.0 |
|  | ±20% | 6.0  | 5.5  | 7.8  | 6.7  | 44.0 | 52.8 |
|  | ±20% | 5.5  | 5.0  | 7.2  | 6.2  | 56.0 | 67.0 |
|  | ±20% | 3.5  | 3.0  | 5.2  | 4.5  | 122  | 135  |

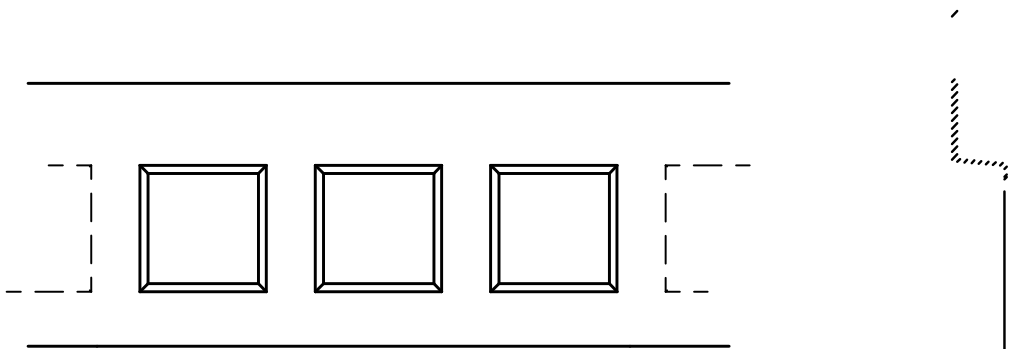
Typical Electrical Characteristics:

# Soldering Reflow:

Preheat condition: 150 ~200℃ / 60~120 sec.  
 Allowed time above 217℃ : 60~150 sec.  
 Max temperature: 260℃ .  
 Allowed Reflow time: 2x max.P1

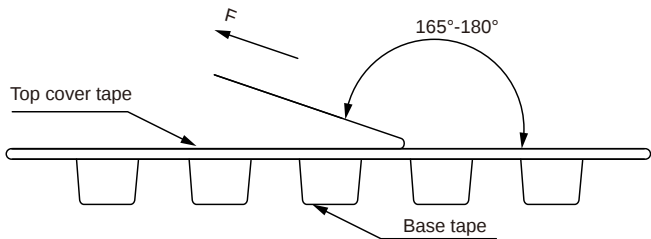
# Packaging Information:

Tape Dimension :



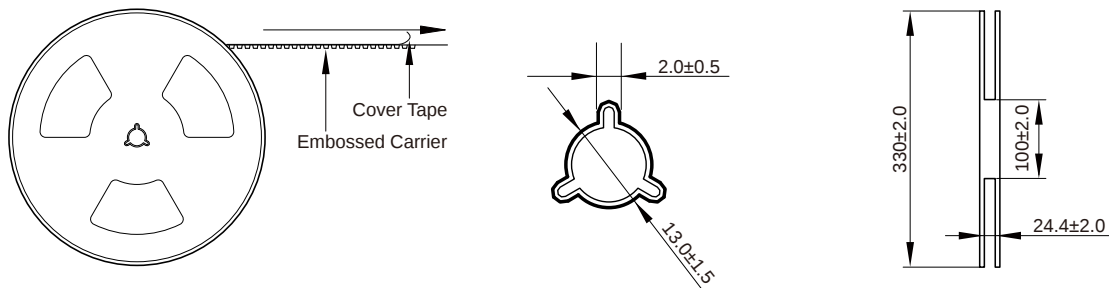
| Series    | A0<br>(mm) | B0<br>(mm) | D<br>(mm) | P0<br>(mm) | P1<br>(mm) | W<br>(mm) | K0<br>(mm) | T<br>(mm) |
|-----------|------------|------------|-----------|------------|------------|-----------|------------|-----------|
| MDA8054HT | 8.9±0.1    | 9.0±0.1    | 1.5±0.1   | 4.0±0.1    | 16.0±0.1   | 24.0±0.3  | 5.9±0.1    | 0.40±0.05 |

Peel force of top cover tape:

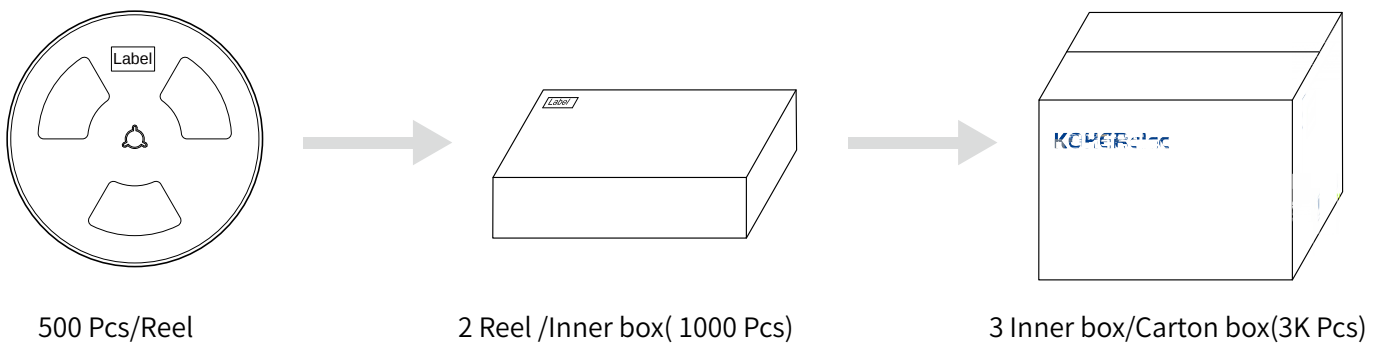


The peel force of top cover tape shall be between 0.1 to 1.27 N

## Reel Dimension: [mm]



## Packaging Quantity:



## Cautions and Warnings:

### Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

### Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does. As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.